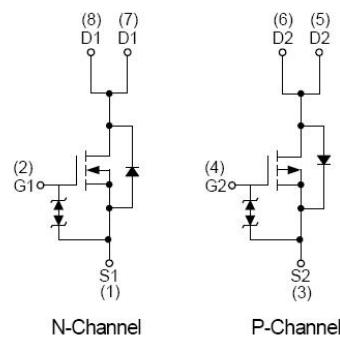


Features

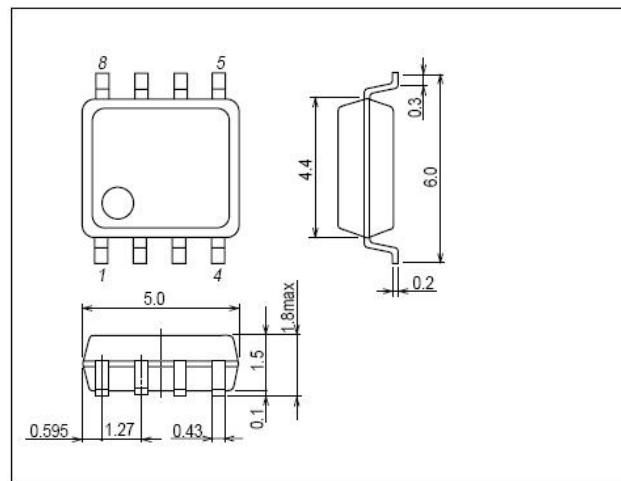
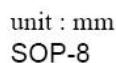
- Low On resistance.
 - 2.5V drive.
 - RoHS compliant.



Specifications

N-Channel

Absolute Maximum Ratings at $T_a=25^{\circ}\text{C}$



Package Dimensions

Dual N+P-Channel Enhancement MOSFET

Si4626



Nanxin

Features

- Low On resistance.
- 2.5V drive.
- RoHS compliant.

N-Channel

P-Channel

Package Dimensions

unit : mm
SOP-8

The diagram illustrates the physical dimensions of the Si4626 SOP-8 package. The top view shows the chip outline with pins numbered 1 through 8. The side view provides a detailed look at the lead profile, with dimensions including height (4.4mm), lead thickness (0.3mm), lead width (0.2mm), lead spacing (1.8mm), lead height (1.5mm), lead thickness (0.1mm), and lead width (0.43mm).

Specifications

N-Channel

Absolute Maximum Ratings at $T_a=25^\circ\text{C}$

Parameter	Symbol	Conditions	Ratings	Unit
Drain-to-Source Voltage	V_{DSS}		20	V
Gate-to-Source Voltage	V_{GSS}		± 12	V
Drain Current (DC)	I_D		7	A
Drain Current (Pulse)	I_{DP}	$PW \leq 10\mu\text{s}$, duty cycle $\leq 1\%$	30	A
Allowable Power Dissipation	P_D	Mounted on a ceramic board ($1000\text{mm}^2 \times 0.8\text{mm}$) 1unit	1.3	W
Total Dissipation	P_T	Mounted on a ceramic board ($1000\text{mm}^2 \times 0.8\text{mm}$)	1.7	W
Channel Temperature	T_{ch}		150	$^\circ\text{C}$
Storage Temperature	T_{stg}		-55~+150	$^\circ\text{C}$

Electrical Characteristics at $T_a=25^\circ\text{C}$

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$I_D=250\mu\text{A}$, $V_{GS}=0\text{V}$	20	-	-	V
Zero-Gate Voltage Drain Current	I_{DSS}	$V_{DS}=20\text{V}$, $V_{GS}=0\text{V}$	-	-	1	μA
Gate-to-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 10\text{V}$, $V_{DS}=0\text{V}$	-	-	± 10	μA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	0.55	0.7	0.95	V
Static Drain-to-Source On-State Resistance	$R_{DS(ON)}$	$I_D=5\text{A}$, $V_{GS}=4.5\text{V}$	-	12	15	$\text{m}\Omega$
	$R_{DS(ON)}$	$I_D=4\text{A}$, $V_{GS}=2.5\text{V}$	-	14	18	$\text{m}\Omega$
Input Capacitance	C_{iss}	$V_{DS}=10\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$	-	500	-	pF
Output Capacitance	C_{oss}	$V_{DS}=10\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$	-	300	-	pF

Electrical Characteristics at $T_a=25^\circ\text{C}$						
Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Drain-to-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	20	-	-	V
Zero-Gate Voltage Drain Current	I_{DSS}	$V_{DS}=20\text{V}, V_{GS}=0\text{V}$	-	-	1	μA
Gate-to-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 10\text{V}, V_{DS}=0\text{V}$	-	-	± 10	μA
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.55	0.7	0.95	V
Static Drain-to-Source On-State Resistance	$R_{DS(\text{ON})}$	$I_D=5\text{A}, V_{GS}=4.5\text{V}$	-	12	15	$\text{m}\Omega$
	$R_{DS(\text{ON})}$	$I_D=4\text{A}, V_{GS}=2.5\text{V}$	-	14	18	$\text{m}\Omega$
Input Capacitance	C_{iss}	$V_{DS}=10\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	-	500	-	pF
Output Capacitance	C_{oss}	$V_{DS}=10\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	-	300	-	pF
Reverse Transfer Capacitance	C_{rss}	$V_{DS}=10\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	-	140	-	pF

Electrical Characteristics at $T_a=25^0C$ (Continued)

Parameter	Symbol	Conditions	Ratings			Unit
			min	Typ	max	
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=10V, R_L=1.35\Omega, R_{GEN}=3\Omega,$ $V_{GEN}=5V$	-	20	-	nS
Rise Time	t_r		-	19	-	nS
Turn-off Delay Time	$t_{d(off)}$		-	65	-	nS
Fall Time	t_f		-	25	-	nS
Total Gate Charge	Q_g	$V_{DS}=10V, V_{GS}=4.5V, I_D=5A$	-	10	-	nC
Gate-to-Source Charge	Q_{gs}		-	2.3	-	nC
Gate-to-Drain "Miller" Charge	Q_{gd}		-	2.9	-	nC
Diode Forward Voltage	V_{SD}	$I_S=1.7A, V_{GS}=0V$	-	0.76	1.2	V

Typical Characteristics at $T_a=25^0C$

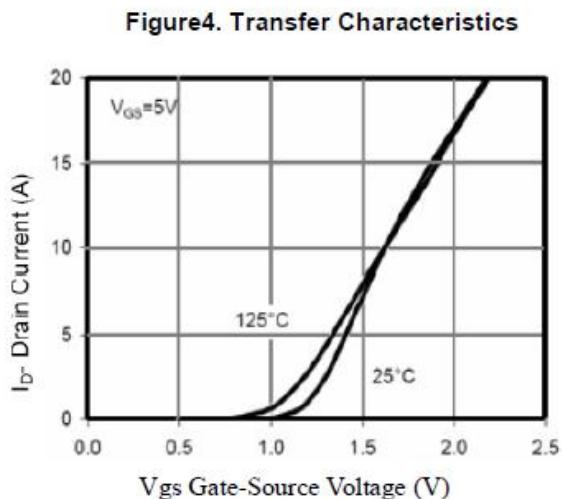
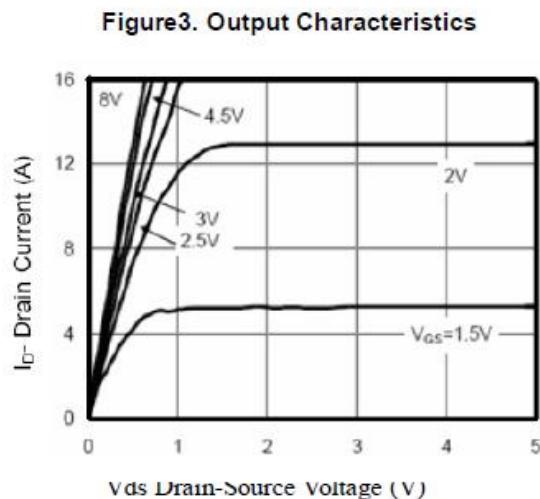
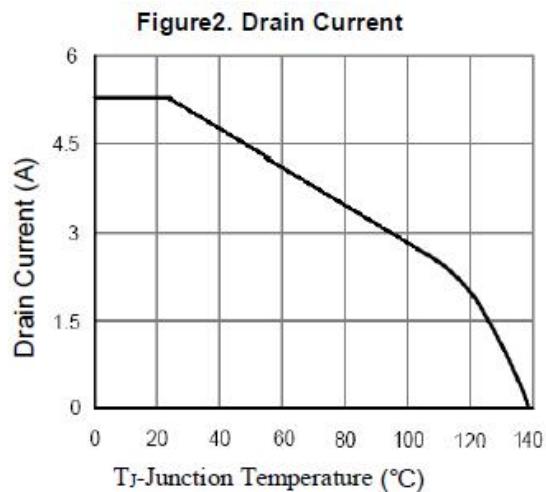
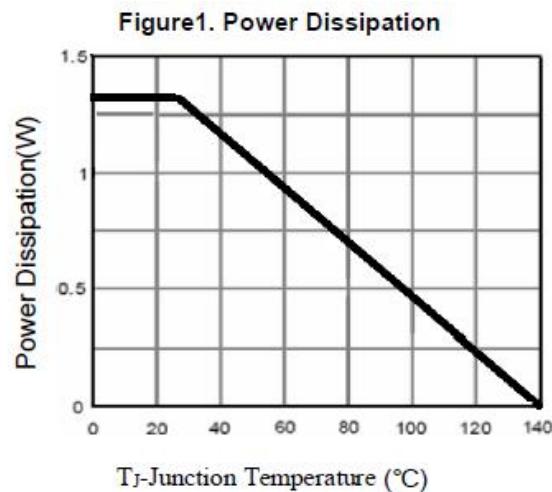


Figure5. Capacitance

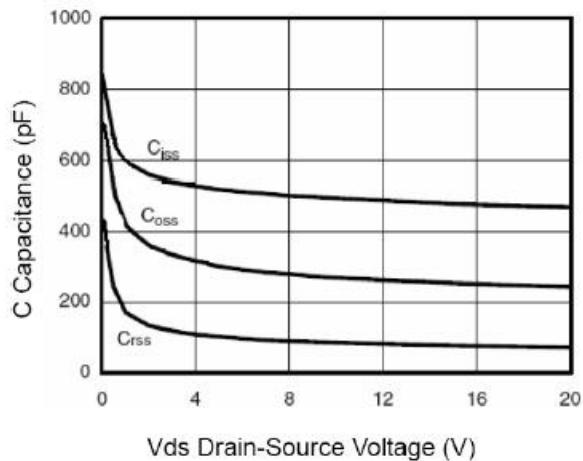


Figure6. $R_{DS(ON)}$ vs Junction Temperature

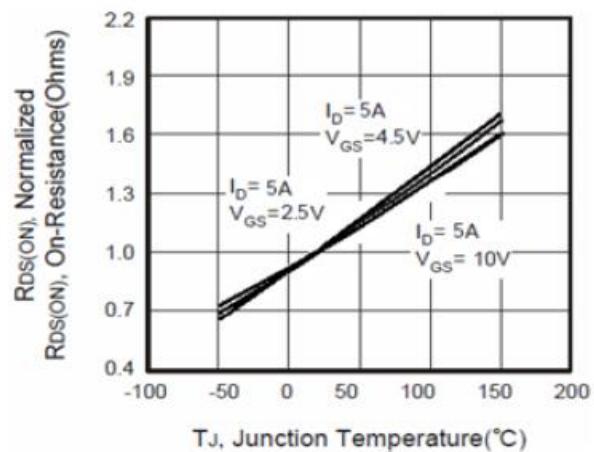


Figure7. Max BV_{DSS} vs Junction Temperature

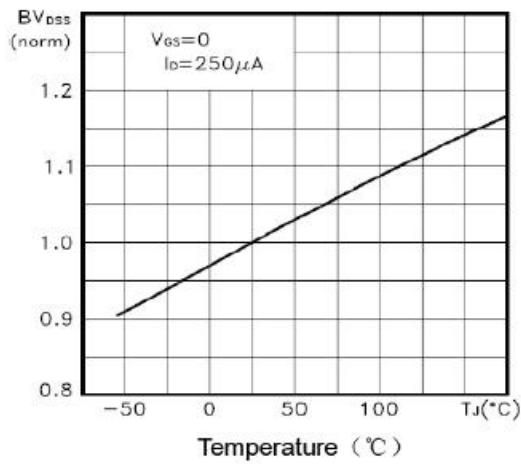


Figure8. $V_{GS(th)}$ vs Junction Temperature

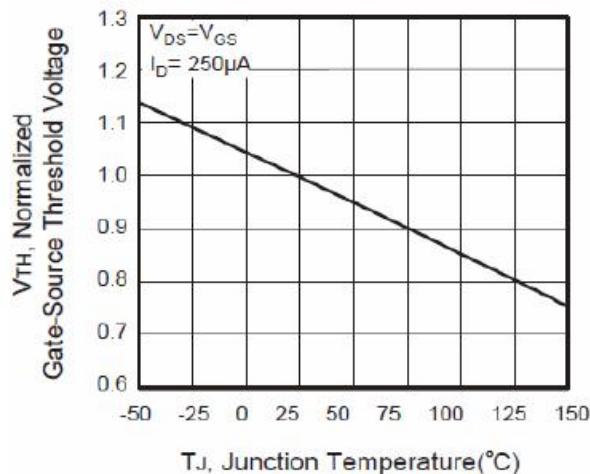


Figure9. Gate Charge Waveforms

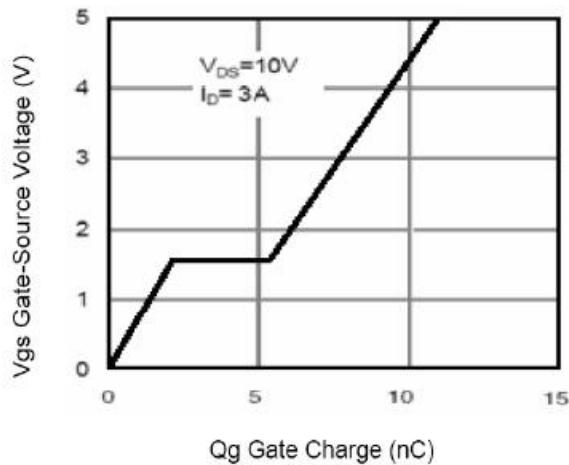


Figure10. Maximum Safe Operating Area

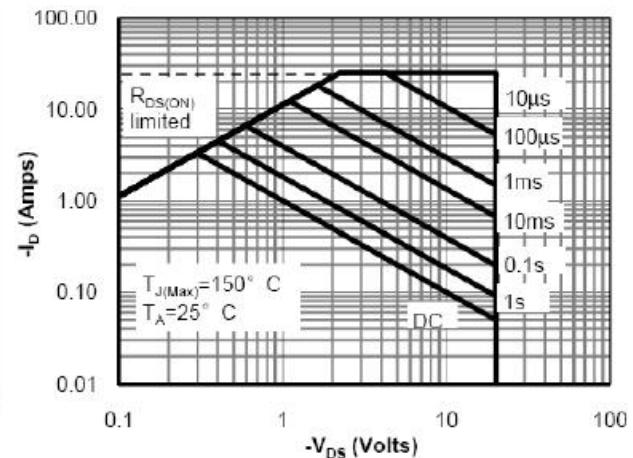
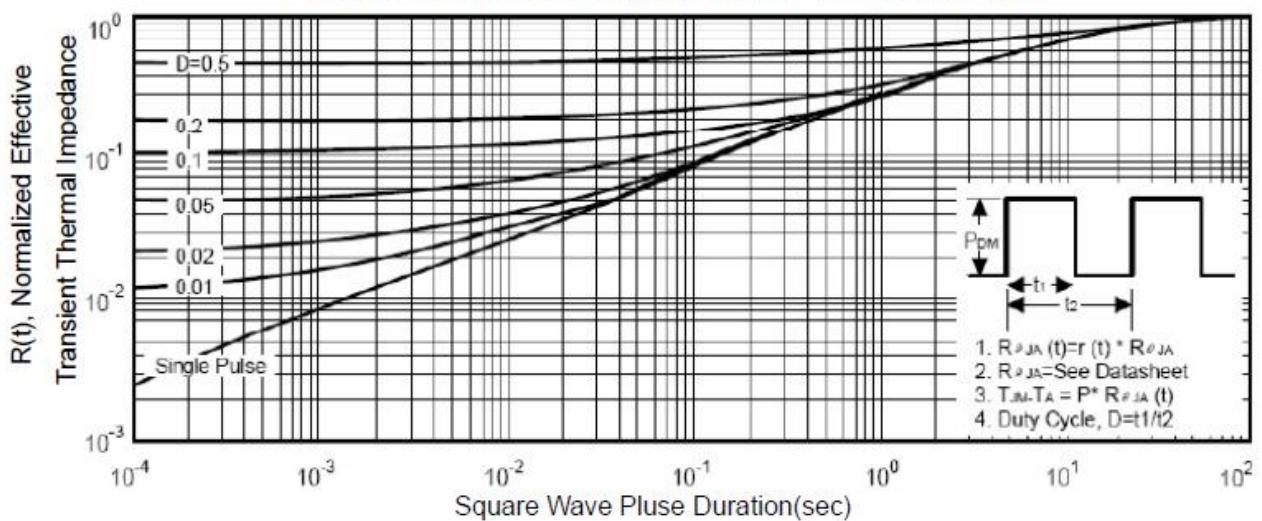


Figure11. Normalized Maximum Transient Thermal Impedance



Specifications

P-Channel

Parameter	Symbol	Conditions	Ratings	Unit
Drain-to-Source Voltage	V_{DSS}		-18	V
Gate-to-Source Voltage	V_{GSS}		± 12	V
Drain Current (DC)	I_D		-7	A
Drain Current (Pulse)	I_{DP}	$PW \leq 10\mu s$, duty cycle $\leq 1\%$	-40	A
Allowable Power Dissipation	P_D	Mounted on a ceramic board ($1000\text{mm}^2 \times 0.8\text{mm}$) 1unit	1.3	W
Total Dissipation	P_T	Mounted on a ceramic board ($1000\text{mm}^2 \times 0.8\text{mm}$)	1.7	W
Channel Temperature	T_{ch}		150	$^{\circ}\text{C}$
Storage Temperature	T_{stg}		-55~+150	$^{\circ}\text{C}$

Electrical Characteristics at $T_a=25^{\circ}\text{C}$

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$I_D=-250\mu\text{A}$, $V_{GS}=0\text{V}$	-18	-	-	V
Zero-Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-20\text{V}$, $V_{GS}=0\text{V}$	-	-	-1	μA
Gate-to-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 12\text{V}$, $V_{DS}=0\text{V}$	-	-	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_D=-250\mu\text{A}$	-0.5	-0.7	-1.4	V
Static Drain-to-Source On-State Resistance	$R_{DS(ON)}$	$I_D=-5\text{A}$, $V_{GS}=-4.5\text{V}$	-	25	32	$\text{m}\Omega$
	$R_{DS(ON)}$	$I_D=-4\text{A}$, $V_{GS}=-2.5\text{V}$	-	35	46	$\text{m}\Omega$
Input Capacitance	C_{iss}	$V_{DS}=-10\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$	-	740	-	pF
Output Capacitance	C_{oss}	$V_{DS}=-10\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$	-	290	-	pF
Reverse Transfer Capacitance	C_{rss}	$V_{DS}=-10\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$	-	190	-	pF
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-10\text{V}$, $I_D=-1\text{A}$, $R_{GEN}=6\Omega$, $V_{GEN}=-4.5\text{V}$	-	12	-	nS
Rise Time	t_r		-	35	-	nS
Turn-off Delay Time	$t_{d(off)}$		-	30	-	nS
Fall Time	t_f		-	10	-	nS
Total Gate Charge	Q_g	$V_{DS}=-10\text{V}$, $V_{GS}=-4.5\text{V}$, $I_D=-5\text{A}$	-	7.8	-	nC

Si4626

Gate-to-Source Charge	Q_{GS}		-	1.2	-	nC
Gate-to-Drain "Miller" Charge	Q_{GD}		-	1.6	-	nC
Diode Forward Voltage	V_{SD}	$I_S = -1.7A, V_{GS} = 0V$	-	-0.8	-1.2	V

Typical Characteristics at $T_a=25^{\circ}\text{C}$

Figure 1:Switching Test Circuit

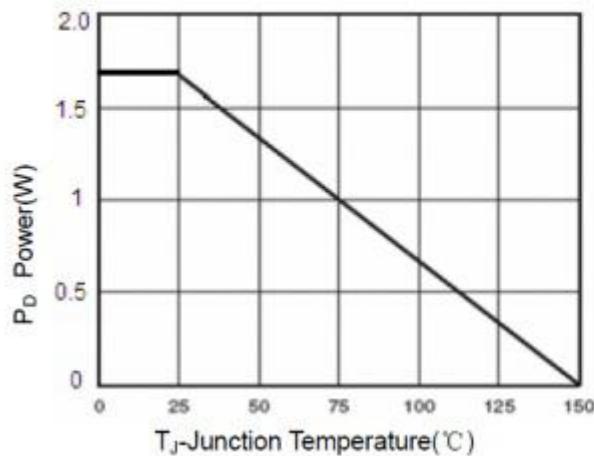


Figure 2:Switching Waveforms

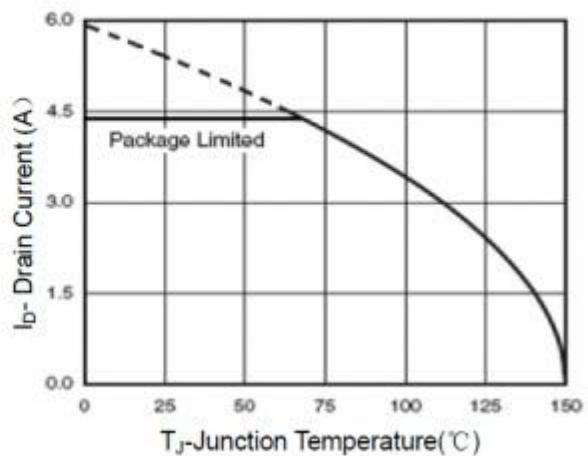


Figure 3 Power Dissipation

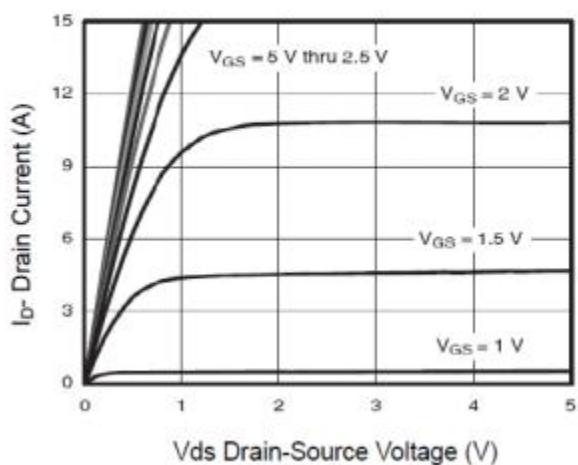


Figure 4 Drain Current

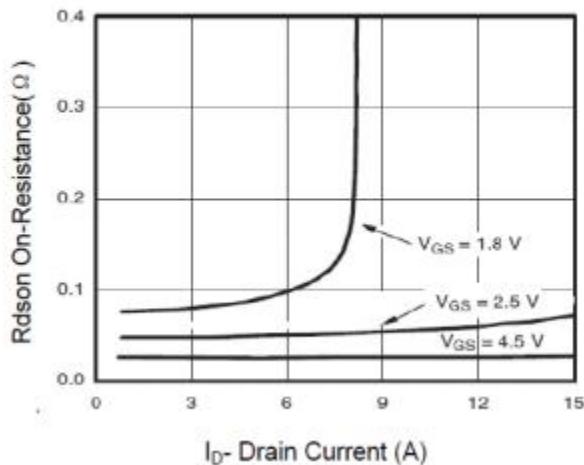


Figure 5 Output Characteristics

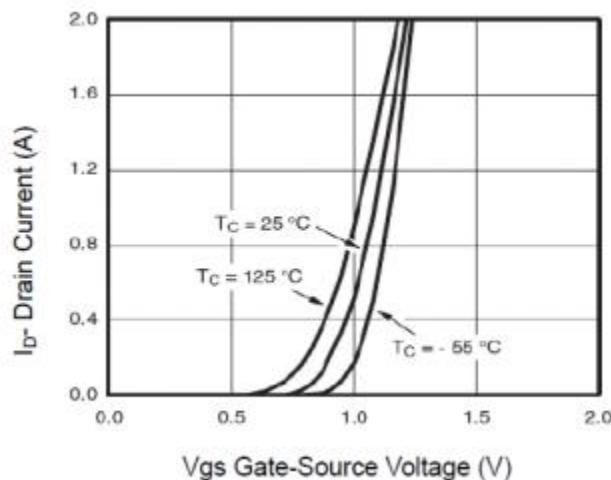


Figure 6 Drain-Source On-Resistance

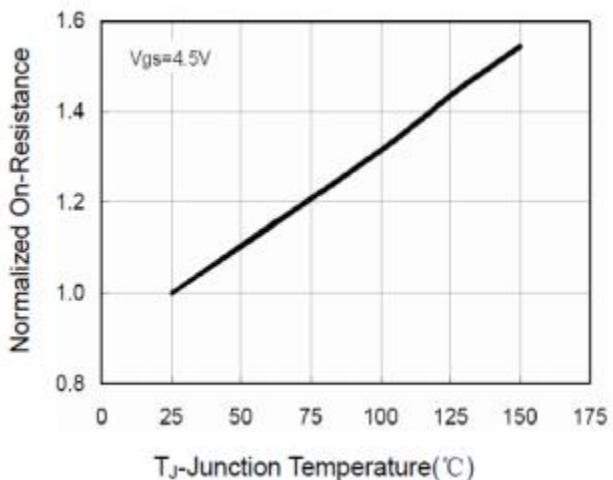


Figure 7 Transfer Characteristics

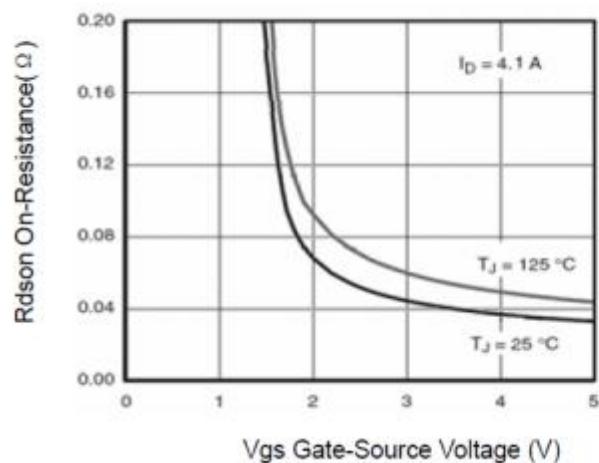


Figure 8 Drain-Source On-Resistance

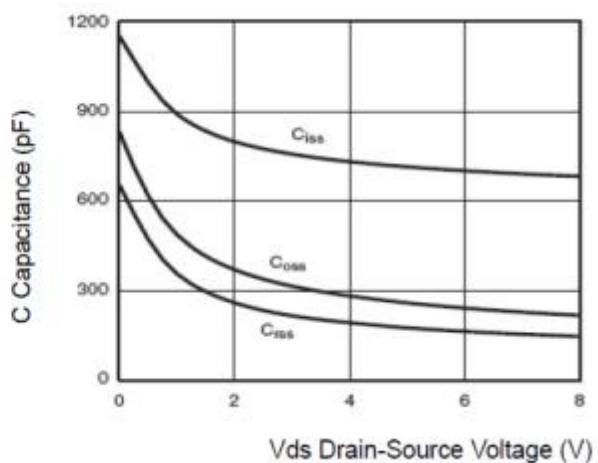


Figure 9 Rdson vs Vgs

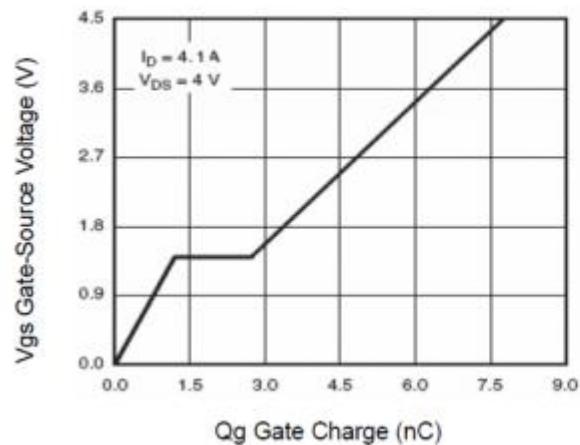


Figure 10 Capacitance vs Vds

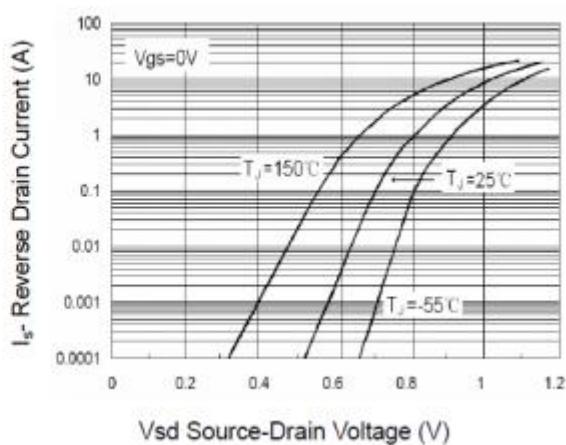
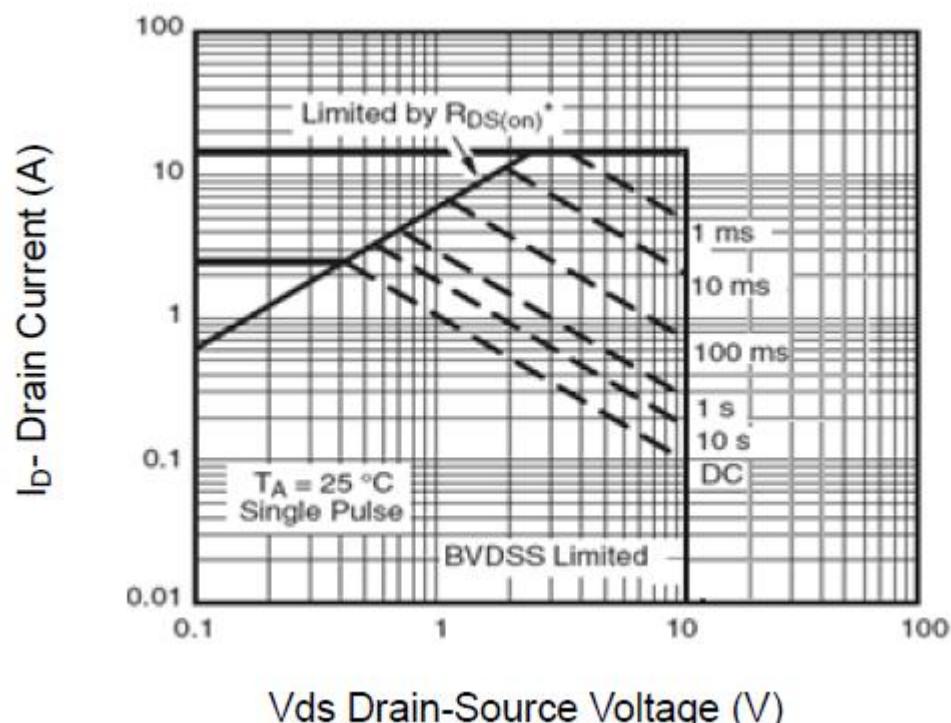


Figure 11 Gate Charge

Figure 12 Source- Drain Diode Forward



V_{ds} Drain-Source Voltage (V)

Figure 13 Safe Operation Area

